

In the Claims:

1. (Original) An electronic component comprising:
a wafer;
a plurality of bond pads disposed on the wafer;
a plurality of functional 3-D structures disposed on the wafer, each functional 3-D structure including a compliant base element;
a plurality of reroute traces, each reroute trace being electrically connected to one of the bond pads and extending onto a surface of one of the functional 3-D structures; and
a plurality of selected 3-D structures disposed on the wafer to provide a mechanical reinforcement, wherein at least some of the selected 3-D structures have a greater mechanical load-bearing capacity than some of the functional 3-D structures.
2. (Original) The component of claim 1 wherein each reroute trace comprises a copper/nickel layer that is covered by a gold layer.
3. (Original) The component of claim 1 wherein the selected 3-D structures have a lower degree of compressibility than the functional 3-D structures.
4. (Currently Amended) The component of claim 1 wherein the selected 3-D structures have a slightly greater height than the functional 3-D structures.
5. (Currently Amended) The component of claim 1 wherein each of the selected 3-D structures includes a compliant base element that has a significantly greater volume than the compliant base element of the functional 3-D structures.

6. (Original) The component of claim 1 wherein each of the selected 3-D structures is protected by a metal cap.
7. (Original) The component of claim 1 wherein each of the selected 3-D structures is surrounded by a metallic supporting ring.
8. (Original) The component of claim 1 wherein the selected 3-D structures are arranged in a regularly distributed manner in an edge region of the wafer.-
9. (Original) The component of claim 1 wherein the selected 3-D structures are arranged in a regularly distributed manner over the wafer.
10. (Original) The component of claim 1 wherein the selected 3-D structures are able to be electrically bonded.
11. (Original) An electronic component comprising:
 - a wafer;
 - a plurality of bond pads disposed on the wafer;
 - a plurality of functional 3-D structures disposed on the wafer, each functional 3-D structure including a compliant base element;
 - a plurality of reroute traces, each reroute trace being electrically connected to one of the bond pads and extending onto a surface of one of the functional 3-D structures;
 - a plurality of other 3-D structures disposed on the wafer to provide a mechanical reinforcement, each of the other 3-D structures having a support structure formed upon a surface of the 3-D structure.

12. (Currently Amended) The ~~electronic~~ component of claim 11 wherein the support structure comprises a metal cap disposed over an entire upper surface of the other 3-D structures.

13. (Currently Amended) The ~~electronic~~ component of claim 11 wherein the support structure comprises a metal ring formed along side surfaces of the other 3-D structures.

14. (Currently Amended) The ~~electronic~~ component of claim 13 ~~claim 11~~ wherein the metal ring is not disposed on any portion of an upper surface of the other 3-D structures.

15. (Currently Amended) The ~~electronic~~ component of claim 11 wherein the support structure is formed from the same material as the reroute traces.

16. (Original) The component of claim 11 wherein each reroute trace comprises a copper/nickel layer that is covered by a gold layer.

17. (Original) The component of claim 11 wherein the other 3-D structures have a lower degree of compressibility than the functional 3-D structures.

18. (Original) The component of claim 11 wherein the other 3-D structures have a greater height than the functional 3-D structures.

19. (Currently Amended) The component of claim 11 wherein each of the other 3-D structures includes a compliant base element that has a ~~significantly~~ greater volume than the compliant base element of the functional 3-D structures.

20. (Original) The component of claim 11 wherein the other 3-D structures are arranged in a regularly distributed manner in an edge region of the wafer.

21. (Original) The component of claim 11 wherein the other 3-D structures are arranged in a regularly distributed manner over the wafer.

22-27. (Canceled)

28. (New) An electronic component comprising:

a wafer;

a plurality of bond pads disposed on the wafer;

a plurality of functional 3-D structures disposed on the wafer, each functional 3-D structure including a compliant base element and having a first height;

a plurality of reroute traces, each reroute trace being electrically connected to one of the bond pads and extending onto a surface of one of the functional 3-D structures;

a plurality of other 3-D structures disposed on the wafer to provide a mechanical reinforcement, each of the other 3-D structures having a second height that is greater than the first height.

29. (New) The electronic component of claim 28 wherein the other 3-D structures include a metal cap disposed over an entire upper surface of the other 3-D structures.

30. (New) The electronic component of claim 28 wherein the other 3-D structures include a metal ring formed along side surfaces of the other 3-D structures.

31. (New) The electronic component of claim 28 wherein the other 3-D structures have a lower degree of compressibility than the functional 3-D structures.

32. (New) The electronic component of claim 28 wherein the other 3-D structures are arranged in a regularly distributed manner in an edge region of the wafer.

33. (New) The electronic component of claim 28 wherein the other 3-D structures are arranged in a regularly distributed manner over the wafer.